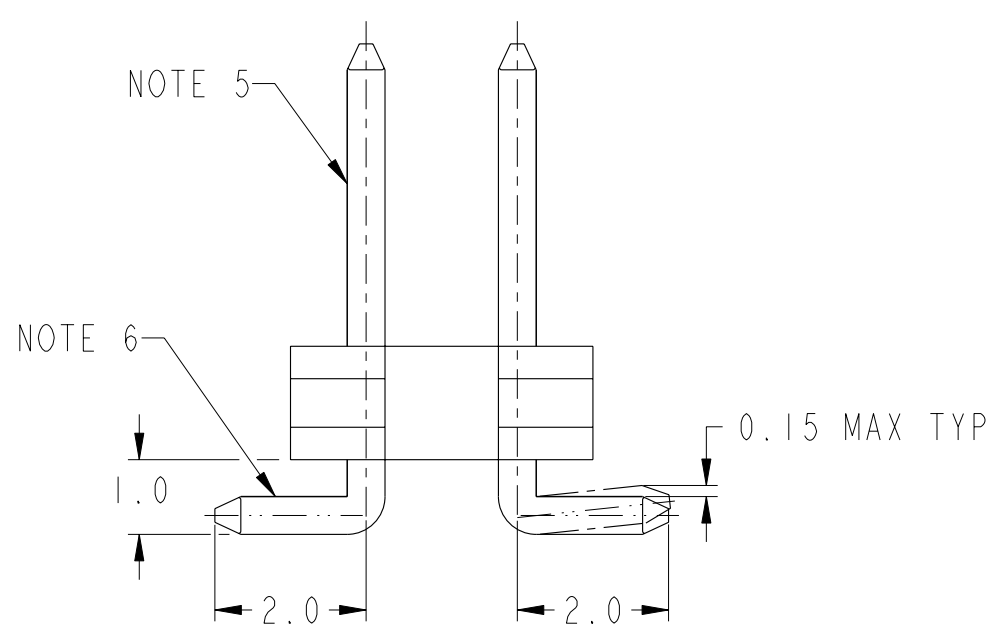
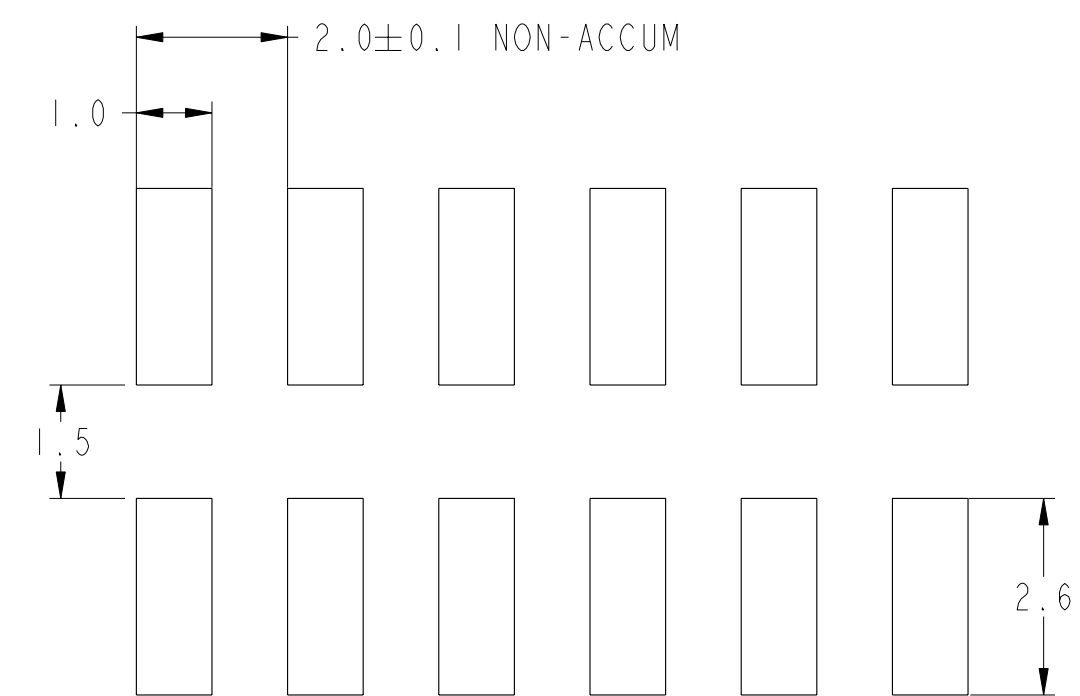
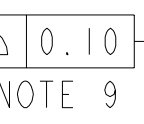
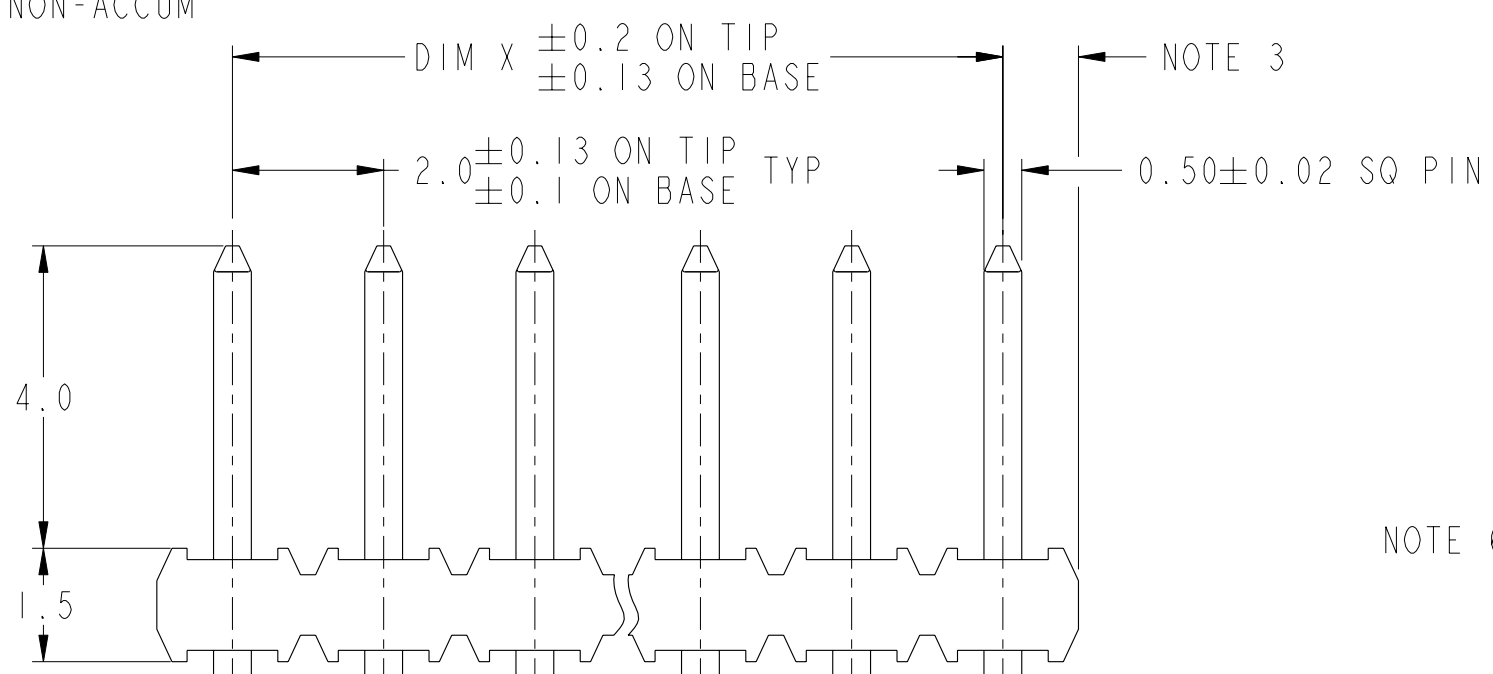
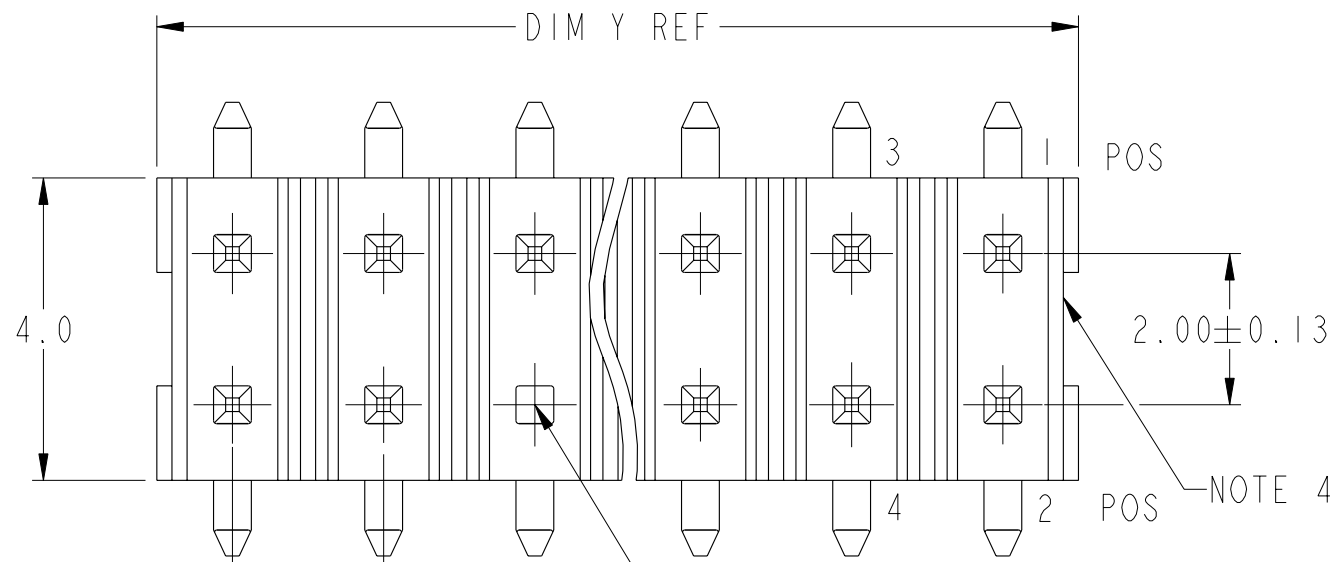




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rev	ecn no	dr	date
E	S20062	JPEH	2002/06/06
F	S04-0172	JPEH	2004/08/11
G	S04-0224	KBM	2004/10/25
H	S05-0060	KBM	2005/02/28
J	S06-0236	KHL	2006/07/17
K	S10-0205	PR	2009/12/17
-	-	-	-

www.fciconnect.com			surface - ☒ ISO 1302	tolerance std ISO 406 ISO 1101	projection	MM
			TOLERANCES UNLESS OTHERWISE SPECIFIED			
Dr	JPEH	2002/06/06	ANGULAR	LINEAR	0.X	±-
Eng	JPEH	2004/08/11			0.XX	±0.25
Chr	KH LEE	2009/12/17	0° ±3°		0.XXX	±-
Appr	JOEY NG	2009/12/17	Product family			ECN S10-0205
			MINITEK			Spec ref -
			POL. MINITEK II			Rev. K
			SMT STR HEADER (DUPLEX)			
			catalog no			
			CUSTOMER			sheet 1 of 2

A

B

C

D

PRODUCT NO. SEE NOTE 8	POS	POL. POS	DIM X	DIM Y
61698-X01	2X22	20	42	44
-X02	2X13	1	24	26
-X03	2X16	3,4,5,6,32	30	32

NOTES:

- MATERIAL:
BODY : HIGH TEMPERATURE THERMOPLASTIC UL 94V-0 BLACK
PIN : COPPER ALLOY
- TOLERANCE UNLESS OTHERWISE NOTED ± 0.25
- DIM 1.0 APPLIES TO MOLDED SIDE(S) ONLY.
IF SIDE(S) ARE BROKEN, DIM 1.5 MAX APPLIES.
- RECESS APPLIES TO MOLDED SIDE(S) ONLY.
- PLATING ON MATING LENGTH:
-3XX --- 0.38 μ m Au OVER 1.27 μ m MIN NICKEL UNDERPLATE.
-5XX --- 0.38 μ m PdNi W Au FLASH OVER 1.27 μ m MIN NICKEL UNDERPLATE.
-6XX --- 0.76 μ m PdNi W Au FLASH OVER 1.27 μ m MIN NICKEL UNDERPLATE.
- SOLDER TAIL PLATING:
a) SOLDER TAIL OF P/N:61698-XXX IS 3.81 μ m MIN TIN/LEAD (90/10) PLATED OVER 1.27 μ m MIN NICKEL UNDERPLATE.
b) SOLDER TAIL OF P/N:61698-XXXLF IS 2.54 μ m MIN 100% MATTE TIN PLATED OVER 1.27 μ m MIN NICKEL UNDERPLATE (LEADFREE).
- PACKAGING:
a) STANDARD PACKAGING IN PLASTIC BAG.
b) SPECIFY 61698-XXXT FOR TUBE PACKAGING.
c) SPECIFY 61698-XXXTR FOR TAP AND REEL PACKAGING.
A PICK-UP CAP IS PROVIDED IN THE CENTRE OF THE PRODUCT (SEE FIG.1) FOR PICK AND PLACE APPLICATION.
d) SPECIFY 61698-XXXTC FOR TUBE PACKAGING WITH PICK-UP CAP IN CENTRE OF PRODUCT(SEE FIG.1).

2

3

4

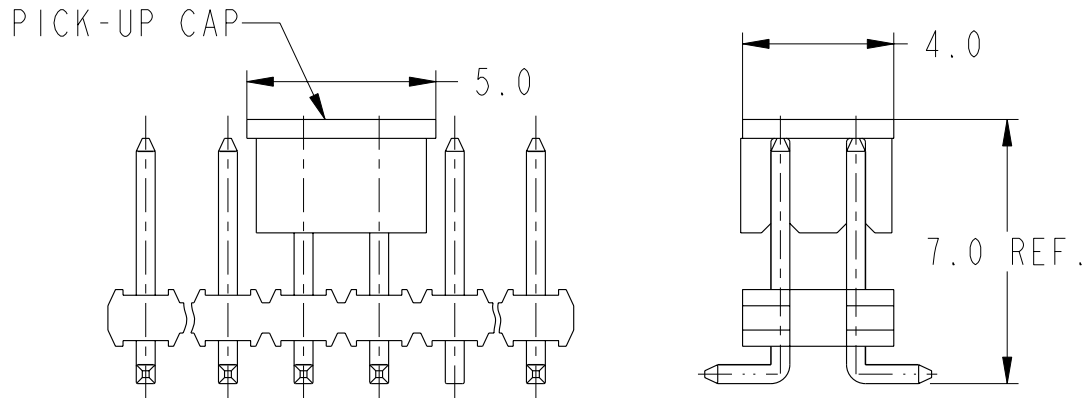
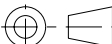


FIG. 1
NOTE 7 (c)&(d)
SCALE 5:1

- PART NUMBER INFORMATION
61698-XYZZLF
LEAD FREE. SEE NOTES 6b,12
TYPE OF PACKAGING SEE NOTE 7
DASH NUMBER
PLATING AT MATING. SEE NOTE 5
BASE NUMBER
- COPLANARITY OF SOLDER LEADS TO BE WITHIN 0.10mm.
- POLARISED BY OMISSION OF PINS. REFER TO TABLE FOR POL. POS.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- A $\triangle K$ SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.

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www.fciconnect.com			surface ISO 1302		- ✓ tolerance std ISO 406 ISO 1101		projection 		MM 		
			TOLERANCES UNLESS OTHERWISE SPECIFIED								
Dr	JPEH	2002/06/06	ANGULAR		LINEAR		0.X	±-	size A3	Scale 10:1	
Eng	JPEH	2004/08/11					0.XX	±0.25			
Chr	KH LEE	2009/12/17	0°	±3°			0.XXX	±-	ECN	S10-0205	
Appr	JOEY NG	2009/12/17	Product family					MINITEK	Spec ref		-
			title POL. MINITEK II SMT STR HEADER (DUPLEX)					dwg no 61698			Rev. K
			catalog no					-	CUSTOMER		sheet 2 of 2